

THERMOFORMED THREE DIMENSIONAL WIRING MODULE

ABSTRACT

The present invention provides a wiring module (1) containing a plurality of laminated polymer layers containing defined electronic circuitry which can be thermoformed into desired three dimensional shapes without damaging the internal wiring at the region of thermoform stress. A thermoformed, three dimensional wiring module is prepared by thermoforming a laminate comprising a plurality of laminated, thermoformable polymer insulating layers containing conductive wiring (3) circuitry on at least one surface of the layers. The layers are assembled to form conductive interconnect paths (2) within the module (1). The module is further characterized in that the conductive wiring circuitry is present only on internal low stress layers of the laminate at the region of thermoformed bends present in the module.

Fig. 1.